

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



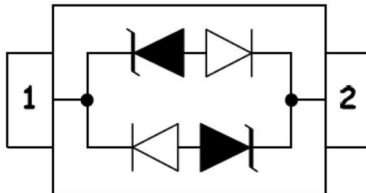
PLED

Product data sheet



SOD-323

PIN CONFIGURATION



FEATURES

- ✧ Transient protection for high-speed data lines
IEC 61000-4-2 (ESD) $\pm 30\text{kV}$ (Contact)
 $\pm 30\text{kV}$ (Air)
IEC 61000-4-4 (EFT) 40A (5/50 ns)
- ✧ Protects one I/O line (bidirectional)
- ✧ Working voltages : 3V, 5V, 8V, 12V, 15V, 18V, 20V, 24V, 36V
- ✧ Low clamping voltage
- ✧ Low leakage current
- ✧ Response time is $< 1\text{ ns}$

MACHANICAL DATA

- ✧ SOD-323 package
- ✧ Flammability Rating: UL 94V-0
- ✧ Packaging: Tape and Reel
- ✧ High temperature soldering guaranteed:
 $260^{\circ}\text{C}/10\text{s}$
- ✧ Reel size: 7 inch
- ✧ MSL1

APPLICATIONS

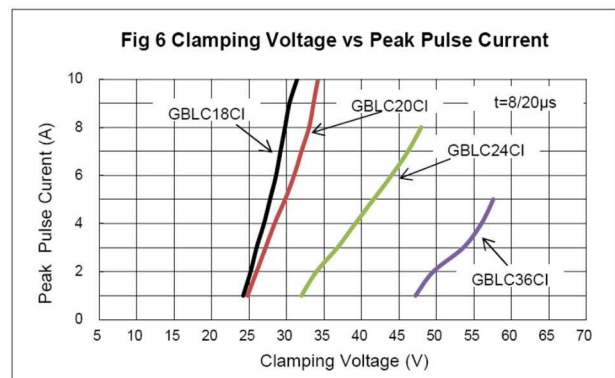
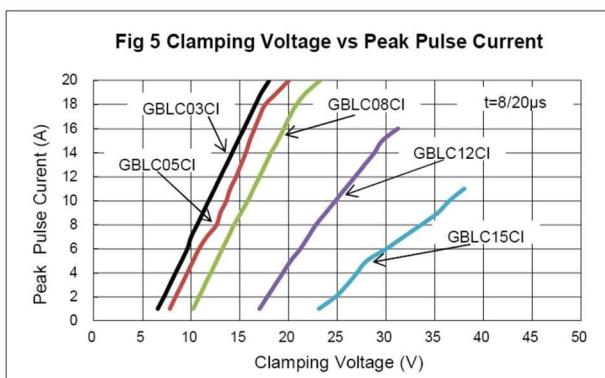
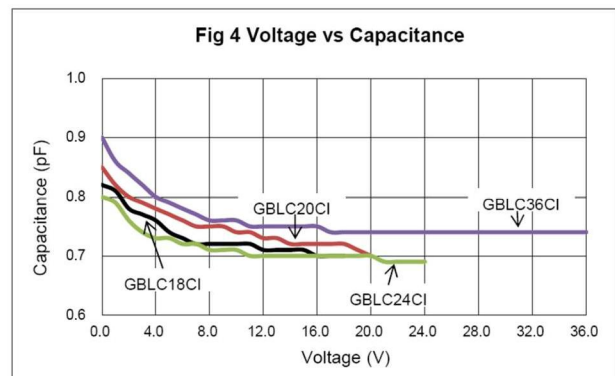
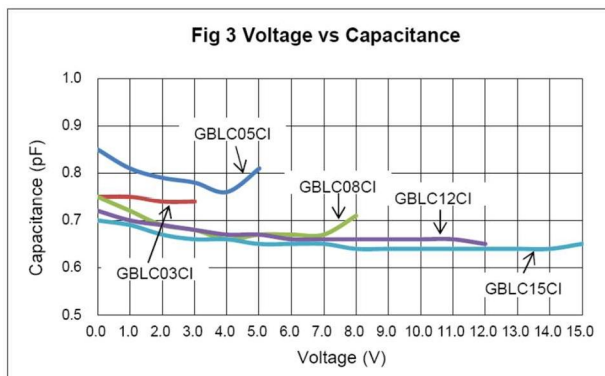
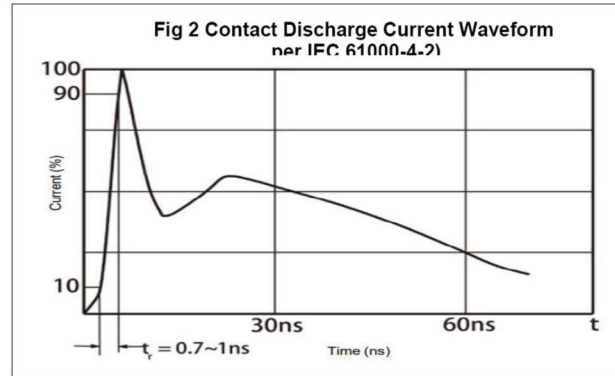
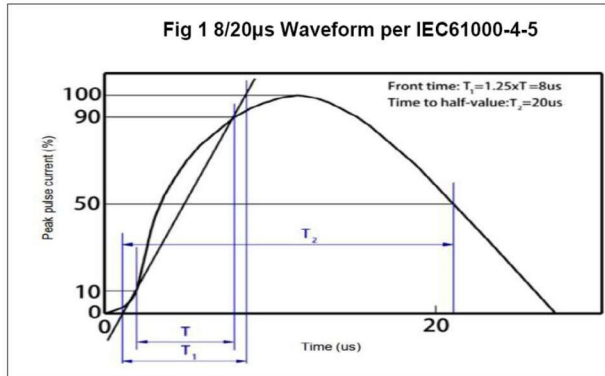
- ✧ Cell Phone Handsets and Accessories
- ✧ Microprocessor based equipment
- ✧ Personal Digital Assistants (PDA's)
- ✧ Notebooks, Desktops, and Servers
- ✧ Portable Instrumentation
- ✧ Peripherals
- ✧ USB Interface

Bi-directional Ultra Low Capacitance TVS Array

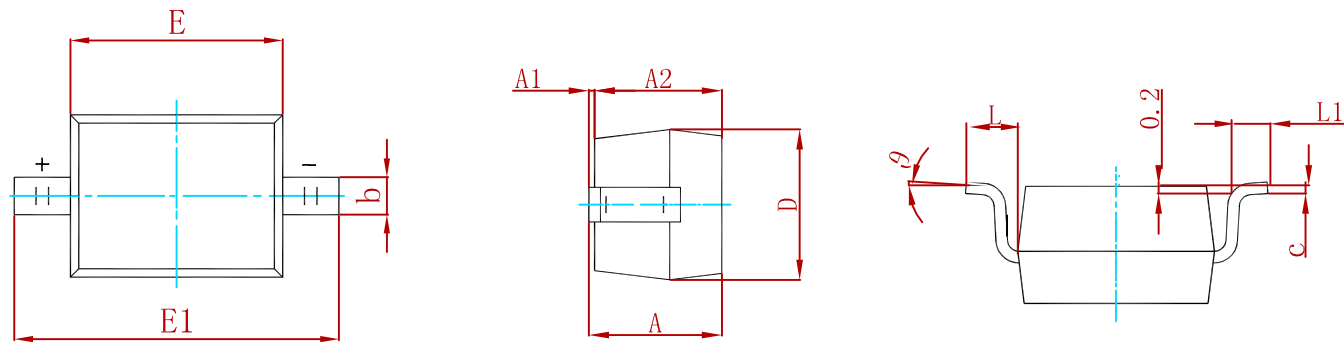
ABSOLUTE MAXIMUM RATING			
Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	± 30 ± 30	kV
P_{PP}	Peak Pulse Power (8/20 μ s)	350	W
T_{OPT}	Operating Temperature	-55/+150	°C
T_{STG}	Storage Temperature	-55/+150	°C
T_L	Lead Soldering Temperature	260	°C

ELECTRICAL CHARACTERISTICS (Tamb=25°C)										
P/N	MARK	V_{RWM} (V)	$V_B@1mA$ (V)	$V_C@1A$ (V)	$V_C@I_{pp}$ (V)		$V_C@I_{pp}$ (V)		I_R (μ A)	C_T (pF)
		Max	Min	Max	Max	I_{pp} (A)	Max	I_{pp} (A)	Max	Typ.
GBLC03CI	CC	3.0	4.0	7.0	13.9	8	20.0	20	5	0.8
GBLC05CI	AC	5.0	6.0	9.8	18.3	8	20.0	18	1	0.8
GBLC08CI	BC	8.0	8.5	13.4	18.5	8	24.0	18	1	0.8
GBLC12CI	DC	12.0	13.3	19.0	24.0	6	28.6	12	1	0.8
GBLC15CI	EC	15.0	16.7	24.0	29.0	5	31.8	10	1	0.8
GBLC18CI	FC	18.0	20.0	35.0	45.0	5	53.0	7	1	0.8
GBLC20CI	GC	20.0	22.0	38.0	45.0	4	55.0	7	1	0.8
GBLC24CI	HC	24.0	26.7	43.0	45.0	3	56.0	6	1	0.8
GBLC36CI	IC	36.0	40.0	60.0	65.0	2	75.0	4.5	1	0.8

ELECTRICAL CHARACTERISTICS CURVE

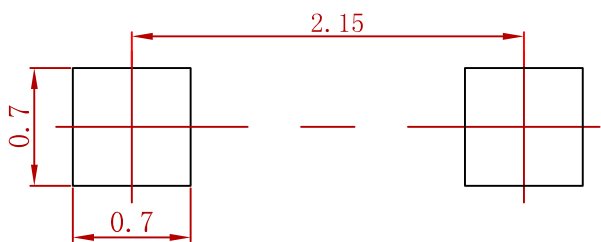


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
GBLCXXCI	SOD-323	3000

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